



Technical Specification

BOOTED SMT LED
WL-L2021B70C-049
Custom White (Lincoln)

Preliminary

Features

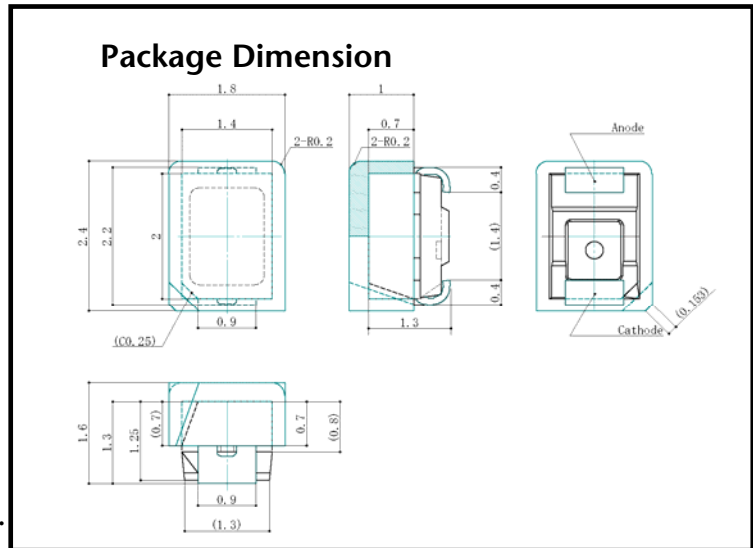
- White package.
- Optical indicator.
- Ideal for backlight and light pipe application.
- Inter reflector.
- Wide viewing angle.
- Compatible with automatic placement equipment.
- Suitable for vapor-phase reflow, infrared reflow and wave solder processes.
- Available on tape and reel (8mm tape).

Description

This LED/boot assembly provides precise color matching to specific x and y coordinates. Due to package design, this assembly has a wide viewing angle for optimized light coupling.

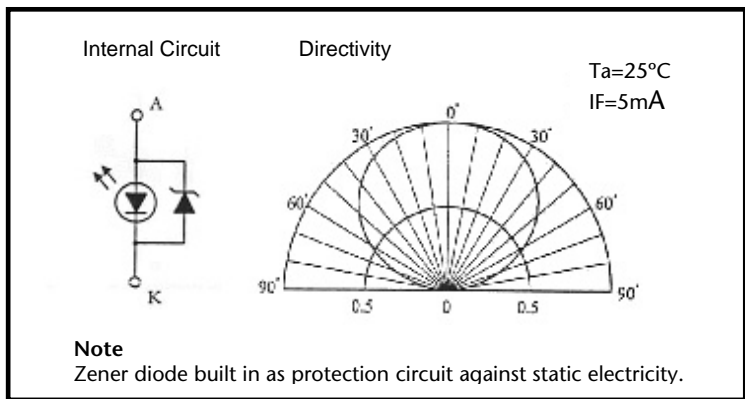
Applications

- Aerospace: backlight for panels, LCD's, switches and symbols.
- Automotive: backlight in dashboards and switches



Notes

- Tolerances are ± 0.2 mm unless otherwise stated.
- Unit = mm.



Part Number	Chip		Boot Color	Revision
	Material	Emitted Color		
WL-L2021B70C-049	InGaN/SiC	White	Yellow	1.0



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Absolute Maximum Ratings at Ta = 25°C

Symbol	Parameter	Rating	Unit
If	Forward Current	10	mA
Topr	Operating Temperature	-40 ~ +100	°C
Tstg	Storage Temperature	-40 ~ +100	°C
Tsol	Soldering Temperature (for 3 seconds)	350	°C
Pd	Power Dissipation	30	mW
If (Peak)	Peak Forward Current (10% Duty Cycle, 10ms Pulse Width Max.)	30	mA

Electronic Optical Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Unit	Condition	
Iv	Luminous Intensity (estimated)	—	TBD	—	mcd	If=5mA	
2θ½	Viewing Angle	—	110	—	deg	If=5mA	
Vf	Forward Voltage	—	2.9	3.1	V	If=5mA	
—	*Chromaticity Coordinates	x	.328	.348	.368	—	If=5mA
		y	.325	.345	.365		

* Per CIE 1931 Chromaticity Diagram.



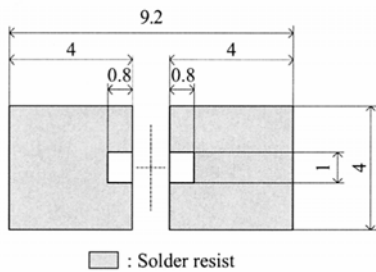
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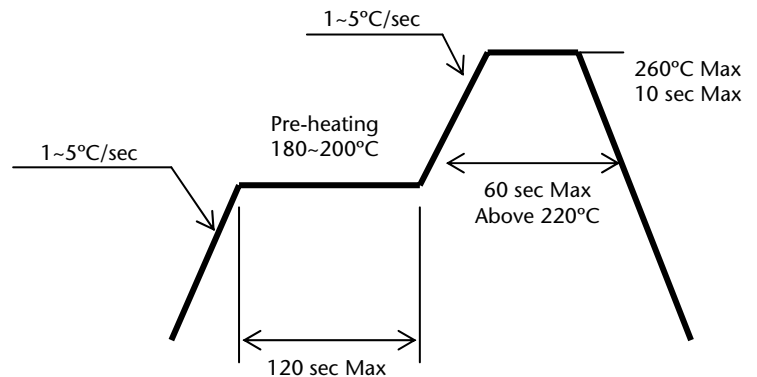
Soldering Conditions

Soldering		Reflow Soldering		
			Lead Free Solder	Lead Solder
Soldering Iron:	20W Max	Pre-Heat:	180~200°C	120~150°C
Temperature:	350°C Max.	Pre-Heat Time:	120 Seconds Max.	120 Seconds Max
Soldering Time:	3 Seconds Max.	Peak Temperature:	260°C Max.	240°C Max
		Soldering Time:	10 Seconds Max.	10 Seconds Max
		Conditions:	Refer to Lead Free Temperature Profile below	Refer to Lead Temperature Profile below

Solder Pad Layout (Unit: mm)



Lead Free Solder Temperature Profile



Lead Solder Temperature Profile

